

Hyoung Joon Kim, Il Kim and Kyung Wook Paik. Kiwon Lee and all are from Korea Advanced Institute of Science and Technology (KAIST). Dr. Lih-Tyng Hwang from Motorola, Inc. presented the award. The winning student author receives a three-year fellowship grant of \$21,000 at his university. For information regarding the Fellowship, please contact Dr. Andrew Skipor, Motorola Chair, at aas002@email.mot.com.



Intel Best Student Paper Award

Submitted by Dr. Rao Bonda, Prog. Chair, 57th ECTC 2007

Intel Corporation sponsored an award for the best paper submitted and presented by a student at the 57th ECTC 2007. To enter the Intel Best Student Paper Award competition, students have checked the "Intel Best Student Paper Award" box in the "Fellowship" section of the on-line abstract submission form. Students considered for the award, are all full time students for at least one semester after the conference conclusion. Only students that were lead authors, and presented the paper at 57th ECTC 2007 were considered. Finalists were determined by review of the completed manuscripts by the judging committee. Manuscripts were reviewed for relevance to the competition topics, technical content, and originality. Finalists were notified by email, and

each finalist submitted an affidavit from their faculty advisor certifying that the student meets the eligibility requirements.

This year's winning paper at 57th ECTC 2007 was presented by Jiongxin Lu of Georgia Institute of Technology and was titled "Tailored Dielectric Properties of High-k Polymer



Composites Via Nanoparticle Surface Modification for Embedded Passives Applications". Her advisor Dr. C.P. Wong is a co-author on the paper. Mr. Debendra Mallik from Intel Corp. presented the award. The student receives a check for \$2500 and a certificate.

Prof. José Schutt-Ainé Appointed Transactions on Advanced Packaging Editor-in-Chief

Submitted by Paul Wesling, CPMT Society VP - Publications



IEEE CPMT Society Board of Governors at June 2nd, 2007 Board Meeting, have nominated Dr. José Schutt-Ainé, Professor of Electrical and Computer Engineering, University of Illinois, Urbana-Champaign, as a second Editor-in-Chief for the Transactions on Advanced Packaging, to work alongside Prof. Ganesh Subbarayan, Profes-

sor of Mechanical Engineering, Purdue University, who continues as Editor-in-Chief. He is nominated for a four-year term commencing in March, 2007, which is renewable. This nomination adopts the model implemented in 2006 for the Transactions on Components and Packaging Technologies, in which the Transactions is divided topically, so that roughly half of the submissions can be handled by each of two Editors-in-Chief.

José's research focus is on signal integrity, electronic packaging, microwave theory and measurements, digital circuit modeling, integration of modeling and simulation tools, high-speed circuit design, and high-performance computation for simulation of packages. He has been active in the Technical Committee on Electrical Design, Modeling and Simulation, and in both the conference on Electrical Performance of Electronics Packaging (EPEP) and the Workshop on Signal Propagation on Interconnects (SPI).

José served as an Associate Editor for the IEEE Transactions on Circuits and Systems from 1997 to 1999, served as Guest Editor for a special section in IEEE Transactions on Advanced Packaging in 2004, and has been an Associate Editor for Transactions on Advanced Packaging since that time.

José E. Schutt-Ainé (M'82-SM'98) received the B.S. degree from MIT in 1981 and the M.S. and Ph.D. degrees from the University of Illinois at Urbana-Champaign (UIUC), in 1984 and 1988, respectively. From 1981 to 1983, he worked at the Microwave Technology Center, Hewlett-Packard, Santa Rosa, CA, as an Application Engineer for microwave amplifiers. During his graduate studies at UIUC, he held summer positions at GTE Network Systems, Northlake, IL, as a Signal Integrity Engineer. In 1996, he worked at Digital Equipment Corporation, Hudson, MA, as a Computer-Aided Design Consultant. He is currently a Professor of electrical and computer engineering at UIUC.

There was a consensus among the key researchers in this field that José would be their choice as Editor-in-Chief, and he has their confidence as he assumes this role. Please assist José as he assumes this new position, and continue to offer support to Ganesh as they work to further improve Transactions on Advanced Packaging.

CPMT Society Officer Interviews:

Interview with Dr. Albert F. Puttlitz, Vice President (Education), IEEE CPMT Society

By Dr. Vasudeva P. Atluri, CPMT Newsletter Editor-in-Chief

Editor: Tell us a little about yourself, and your family

Al: I was born and lived in Kingston, New York until I left for college. I have an Associate Degree in Mechanical Technology from the State University of New York at Canton, New York (1956), a Bachelor of Science Degree in Mechanical Engineering from Rochester Institute of Technology, Rochester, New York (1959), and a Master of Science Degree in Engineering Mechanics from Michigan Technological University, Houghton, Michigan (1961).



I began my career with the IBM Federal Systems Division in Kingston, New York in 1956. I took three leaves of absence from IBM to pursue my Bachelors, Masters and Doctoral degrees. I received my Ph.D. degree in Engineering Mechanics from Michi-